

THE STANDARD OF FLEXIBILITY

XM520



XM520 is a general purpose chip mounter with the best-in-class productivity and quality. It also has flexibility to cover various products and a wide range of line combination and option. Its innovative features can maximize user convenience for a rapid job change.



Model Name			XM520	
Head Type			HS (High Speed) Head	HP(High Precision) Head
The Number of Spindles			10 Spindle x 2 Gantry	5 Spindle x 2 Gantry
Placement Speed			100,000 CPH (Optimum)	36,000 CPH (Optimum)
Placement Accuracy	Chip		$\pm 22 \mu\text{m}$ @ Cpk ≥ 1.0	$\pm 35 \mu\text{m}$ @ Cpk ≥ 1.0
	IC		$\pm 25 \mu\text{m}$ @ Cpk ≥ 1.0	$\pm 20 \mu\text{m}$ @ Cpk ≥ 1.0
Component Range	Size		0201 ~ L150 x 55 mm	0402 ~ L150 x 75 mm
	Max. Height		15 mm	30 mm
	Force (Max)		-	~100N
	Weight		-	~300g
PCB Size (mm)	Min.		L50 x W40	
	Max.	Single Mode	L625~L900(2 clamp) x W460~590 (Option L1,200*)	
		Dual Mode	L625~L900(2 clamp) x W250~315 (Option L1,200*)	
PCB Thickness (mm)			0.3~4.2	
Feeder Capacity			120 ea / 112 ea (Docking Cart)	
Weight (H900mm Standard)	Fixed Type		Approx. 1,815 kg	
	Docking Type		Approx. 1,770 kg (without Doking Cart)	
External Dimension (mm)			L1,430 x D1,870 x H1,994	

* For the specifications of the L 1,200 mm option, please contact our sales

※ The specification in this catalog is based on value measured at an optimized condition. The result may vary depending on the operating condition.



**Best Speed for 10 Spindle Solution
Max. 100,000 CPH**

Possible to have a high productivity with the maximized one-time handling quantity, the best-in-class high-speed head (15mm pitch & height), and the odd-form head (30mm pitch & height).



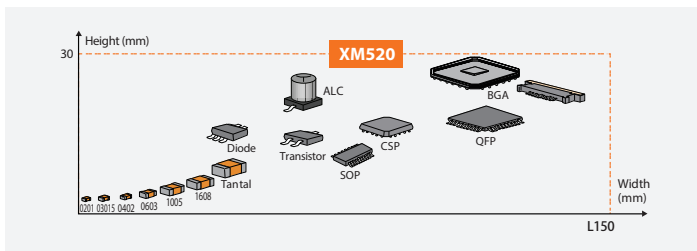
**Best Accuracy in class
± 22 μm @ Cpk ≥ 1.0 (Chip)
± 20 μm @ Cpk ≥ 1.0 (IC)**

Achieves the best-in-class placement accuracy and maintains a high component quality with the automatic quality control from runtime calibration and nozzle maintenance.

Flexible Production

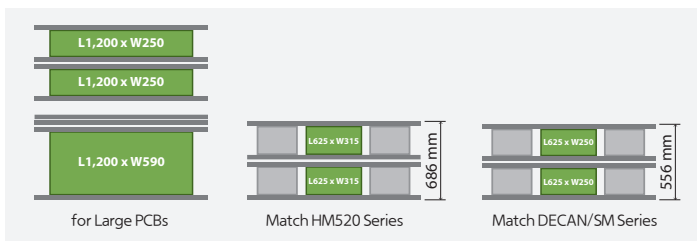
Wide Component Application

Possible to place components from 0201 microchips up to L150 mm with a height of up to 30 mm.



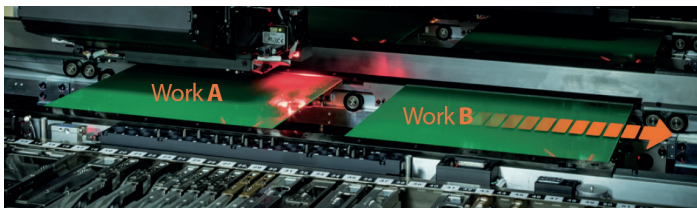
Multiple line combination with flexible PCB coverage

PCB coverage up to L1200 x 590 mm, allowing optimal in-line combination to suit any production environment.



Actual Productivity Increase with Dual Work Zone

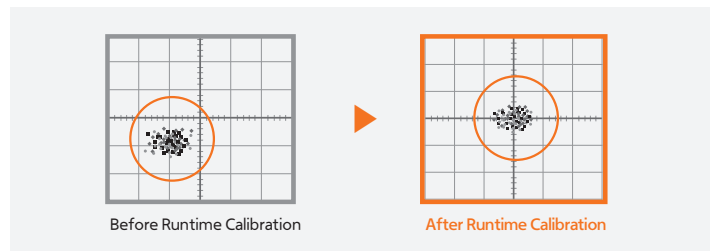
Productivity enhanced with reduced loading time with simultaneous job between Work A and B. Work A can be ready with the next PCB while Work B completes the previous PCB.



Convenient Operation

Maintain placement accuracy with automatic calibration during a production

Maintains placement accuracy throughout production by applying major calibration at the set-up stage during the production.



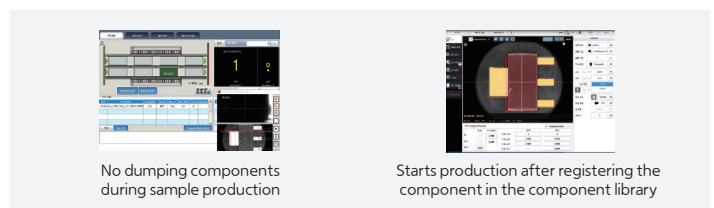
Automated Placement Point Teaching

With the inspection and modification of placement points on standard chips, it significantly reduced the time required to check and fine-tune the placement coordinates during a model change.



Zero Waste from a New Product (Sample)

Components are not wasted with a simple error in recognition during the sample production stage. The component information and PCB coordinates are revised and reused for the next production.



• The specification in this catalog is actual value measured under designated condition. These are subject to change without prior notification.
• The above value may vary depending on operating condition. For inquiry, please contact our sales representative or visit our website.